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# New Pixel Circuits for Controlling Threshold Voltage by Back-gate Bias Voltage using Crystalline Oxide Semiconductor FETs

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### **Abstract**

We devised a threshold voltage compensation pixel circuit using back-gate bias voltage. Variations in threshold voltage can be reduced to 10% while improving the saturation characteristics of a driving transistor. We fabricated a 5.29-in Quad-VGA OLED display using this pixel circuit.

### **Author Keywords**

oxide semiconductor; CAAC-IGZO; OLED; threshold voltage compensation

### 1. Introduction

Kimizuka et al. synthesized  $InGaO_3(ZnO)_m$  (IGZO) for the first time in 1985, and proposed its use as a semiconductor element and stated the necessity of increasing the purity of IGZO in 1987 [1]. Cillessen et al. disclose the application of  $InO_x$ ,  $GaO_x$ , or  $ZnO_x$  or mixtures or compounds of these oxides to liquid crystal displays (LCDs) [2].

Transparent amorphous oxide semiconductors (TAOS) are proposed by Kamiya, Hosono, et al. and they claim amorphous structures to be ideal [3,4], while we have proposed crystalline IGZO.

We discovered c-axis-aligned crystalline (CAAC-IGZO) and nanocrystalline IGZO (nc-IGZO), which have crystal morphologies different from those of single crystal IGZO and amorphous IGZO [5,6]. Characteristics of the CAAC- and nc-IGZOs have been revealed [7], and they appear to be formed by arranged or stacked nanocrystals (pellets) (1-3 nm thick and 0.7–0.8 nm wide each) [8]. In CAAC-IGZO films, atomic arrangement parallel to a substrate surface is observed by cross-sectional transmission electron microscopy (TEM). By X-ray diffraction (XRD) analysis, a peak at approximately 31°, which indicates the c-axis alignment, is detected, but a-b plane alignment is not observed [8]. No clear grain boundary is observed by plan-view TEM [8]. CAAC-IGZO field-effect transistors (FETs) have an extremely small off-state current on the order of voctoamperes per micrometer ( $10^{-24}$  A/µm) because of low carrier density [9,10]. These FETs are less likely to suffer from short-channel effects and therefore very suitable for miniaturization [10].



**Figure 1.** Classification of IGZO in terms of crystal morphology

We have reported on LCDs and tandem OLED displays using IGZO transistors with an ultra-low off-state current [11-14]. Regarding OLED displays, we have studied threshold voltage compensation for pixel circuits [14].

Generally, the threshold voltage ( $V_{\rm th}$ ) of a Si transistor is easily controlled by impurity doping. However, the fabrication process of IGZO FETs does not include such a step by which  $V_{\rm th}$  is easily controlled. Variation in  $V_{\rm th}$  makes it difficult to keep the value of current flowing through an OLED constant. This might decrease the quality of an OLED display whose emission luminance depends on the value of the current. Using a  $V_{\rm th}$  compensation circuit is a useful way of suppressing a decline in display quality due to  $V_{\rm th}$  variation.

A possible cause of the declining quality of an OLED display is poor saturation characteristics of a driving transistor. When a transistor has poor saturation, the current value of the transistor depends on the drain–source voltage even in a saturation region. Furthermore, current flowing through the OLED changes accordingly when the operating point of the OLED changes because of variables such as time degradation.

We devised a novel pixel circuit for compensating  $V_{\rm th}$  of a driving transistor considering these two causes and increasing the saturation of the transistor. Each pixel circuit includes six transistors and has a driving transistor  $V_{\rm th}$  compensation function using back-gate bias voltage. We built a prototype of a 5.29-in Quad-VGA OLED display using this pixel circuit.

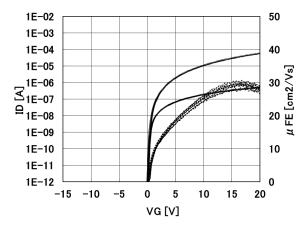
# 2. *I–V* Characteristics of CAAC-IGZO FETS

Fig. 2 shows the I-V characteristics of CAAC-IGZO FETs. The FETs used for the measurement have a channel width of 3  $\mu$ m, a channel length of 3  $\mu$ m, and a back-gate. The FET characteristics were measured in 9 points in a 3.5th generation mother glass. The median and variation  $3\sigma$  of the  $V_{th}$  were 0.44 V and 0.30 V, respectively. The FETs exhibited mobilities of  $30~\text{cm}^2/\text{V}\cdot\text{s}$  or higher. The advantage of including a back-gate in an FET is that FET saturation characteristics are improved and the drain-induced barrier lowering effect is thus

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reduced. A channel-length modulation coefficient of a single-gate FET without a back-gate is approximately  $0.05 \, \mathrm{V}^{-1}$ , whereas that of a back-gate FET is approximately  $0.009 \, \mathrm{V}^{-1}$ , i.e., the saturation characteristics are improved [15]. Another advantage is that  $V_{\mathrm{th}}$  of an FET can be electrically controlled. Fig. 3 shows the measurement results of the back-gate dependence of  $V_{\mathrm{th}}$  of a pixel FET. We measured the  $I\!-\!V$  characteristics while changing the  $V_{\mathrm{bgs}}$  and fixing the source potential of an FET to calculate  $V_{\mathrm{th}}$  that are plotted. As shown in Fig. 3, the  $V_{\mathrm{th}}$  decreases as  $V_{\mathrm{bgs}}$  increases, whereas the  $V_{\mathrm{th}}$  increases as  $V_{\mathrm{bgs}}$  decreases

The  $V_{\rm th}$  amount shifts linearly with respect to the  $V_{\rm bgs}$ . Note that the shift amount of  $V_{\rm th}$  here depends on the thickness and the relative permittivity of an intermediate layer between the channel and back-gate portions. As the thickness of the intermediate layer increases and the relative permittivity decreases,  $V_{\rm bgs}$  has less influence on the  $V_{\rm th}$ .



**Figure 2.** *I*–*V* characteristics of CAAC-IGZO FETs ( $W/L = 3 \mu m/3 \mu m$ ,  $V_{ds} = 0.1 \text{ V}$ , 20 V)

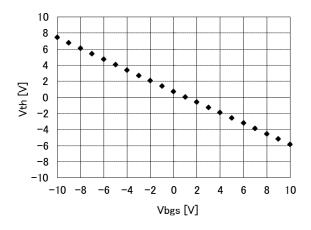


Figure 3. Back-gate dependence of the  $V_{th}$  of FET ( $W/L=3~\mu m/3~\mu m,~V_{ds}=20~V$ )

# 3. Threshold Voltage Compensation Circuit for Pixels of OLED Display

We designed the pixel circuit shown in Fig. 4. Each pixel includes six transistors (Tr1 to Tr5 and DrTr), two capacitors (C1 and C2), three power supply lines (ANODE,  $V_0$ , and  $V_1$ ), one data line (DATA), three scan lines (G1, G2, and G3), and an OLED. Fig. 5 shows the operation of the pixel circuit.

In Period I, initialization is performed. Tr2, Tr3, and Tr4 are on; Tr1 and Tr5 are off; and  $V_0$  is applied to a back-gate of DrTr in Period I. The source potential is the sum of the CATHODE potential and threshold of the OLED ( $V_{thOLED}$ ), so that  $V_{bgs}$  can be large;  $V_{th}$  of the driving transistor negatively shifts to make the transistor normally on.

In Period II, the  $V_{\rm th}$  of the DrTr is compensated. Here only Tr2 and Tr3 are on, the gate-source node of the DrTr is thus electrically connected, and the back-gate potential of the DrTr remains  $V_0$ . The DrTr is turned on because it is normally on, and the source potential gradually increases. Because the potential  $V_0$  is fixed,  $V_{\rm bgs}$  gradually decreases and the negative  $V_{\rm th}$  increases to 0. The gate-source potential ( $V_{\rm gs}$ ) is 0 V here, and the  $V_{\rm th}$  is equal to  $V_{\rm gs}$  when  $V_{\rm th}$  is 0 V, whereby the driving transistor is turned off. At this time, the back-gate voltage is held by C2, so that the characteristics of the DrTr can be fixed in the state of  $V_{\rm th}=0$  V.

In Period III, data writing is performed. Tr1 and Tr5 are turned on, and the potential of  $V_{\text{data}}$ – $V_1$  is held by C1.

Finally, light is emitted in Period IV. Only Tr4 is turned on, and the DrTr accordingly supplies current depending on  $V_{\rm gs}$ – $V_{\rm th}$ . However, current depending only on  $V_{\rm gs}$  with which  $V_{\rm th}$  variation is canceled, i.e.,  $V_{\rm data}$ – $V_{\rm l}$ , flows because the  $V_{\rm th}$  of the DrTr is compensated to be 0 V. Consequently, light emission can be performed without dependence on the  $V_{\rm th}$  of the DrTr.

Note that this pixel circuit can be driven with five transistors other than Tr2. However, if it is driven by a transistor other than Tr2, only when the source potential of the DrTr is charged in Period II does  $V_{\rm gs}$  become 0. This method requires consideration of current flowing into the OLED in Period I that depends on  $V_{\rm data}$ , which is written in the previous frame.

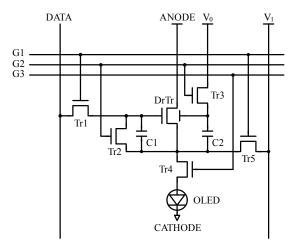


Figure 4. Pixel circuit diagram

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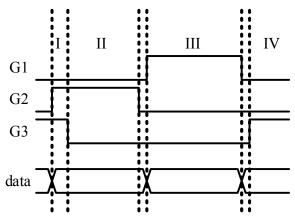


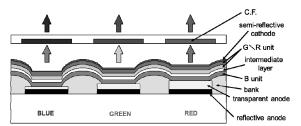
Figure 5. Timing chart of pixel circuit

# 4. Panel Configuration

We built a prototype of a 5.29-in Quad-VGA OLED display. The panel specifications are listed in Table 1. The pixel density and aperture ratio are 302 ppi and 61.0%, respectively. Top emission white electroluminescence (EL) elements and color filters (CF) were employed for the full-color panel (Fig. 6). The white EL element has a two-layered tandem structure in which an emission unit containing a blue fluorescent material and an emission unit containing green and red phosphorescent materials are connected in series (Fig. 7). A scan driver is integrated on the glass substrate, and the source driver is a chip on film (COF). The pixel circuit we designed achieves a temporal separation between an operation in a  $V_{\rm th}$  compensation period and that in a data writing period, corresponding to not only linear sequential driving but also dot sequential driving. The prototype of the OLED panel is driven with dot sequential driving in which a demultiplexer separates three colors, RGB.

Table 1. Panel specifications

Specifications	
Screen diagonal	5.29 in
Driving method	Active matrix
Number of effective	960 × RGB × 1280
pixels	(Quad-VGA)
Pixel density	302 ppi
Pixel pitch	28 $\mu$ m $ imes$ RGB $ imes$
	84 μm
Aperture ratio	61.0%
Pixel arrangement	RGB stripe
Pixel circuit	6Tr + 2C/cell
Source driver	COF + DeMUX
Scan driver	Integrated



**Figure 6.** Cross section of EL elements with coloring method

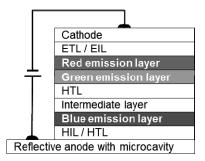


Figure 7. Cross-sectional structure of white EL layer

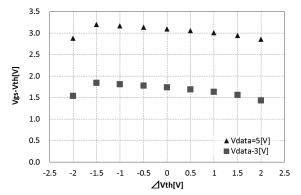
### 5. Results

Fig. 8 shows a picture displayed by the panel that we fabricated. The panel displays images without problems such as display unevenness. Fig. 9 shows simulation results with the changing  $V_{\rm th}$  of the driving transistor. Here we obtain  $V_{\rm gs}$ - $V_{\rm th}$ plotted on the vertical axis by subtracting the  $V_{\rm th}$  of the driving transistor from that of the transistor in an emission period in Period IV. The slope of the graph is 0 when the  $V_{th}$ compensation is completed because  $V_{\rm gs}$ - $V_{\rm th}$  is independent of the  $V_{\rm th}$ . The simulation results show that, in the circuit we designed, variation in a range from the typical  $V_{\rm th}$  to  $\pm 1.5$  V can be suppressed to approximately 10%. In principle, the pixel circuit can compensate the  $V_{\rm th}$  variation in a range of  $V_{\rm th}$  from 0 to a value positively shifted by a potential of  $V_0$ -(Cathode+ $V_{\text{thOLED}}$ ) in the normally off transistor, and in a range of  $V_{th}$  from 0 to a value negatively shifted by a potential of Anode- $V_0$  in the normally on transistor. Note that when the effect of  $V_{th}$  control by a back-gate bias is small depending on the conditions of the intermediate layer between the channel and back-gate portions, the amount of variation ranges within this  $V_{\rm th}$  control. Although the  $V_{\rm th}$  compensation range is not wide, a CAAC-IGZO transistor with less variation even in a 3.5th generation mother glass is capable of high-accuracy compensation. If variation in the  $V_{th}$  of the driving transistor is limited in the range of the normally off transistor, the anode can serve as a power source of the power supply line  $V_0$ , in which case one power supply line  $V_0$  in a pixel can be removed.

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Figure 8. Display picture



**Figure 9.** *V*<sub>th</sub> variation dependence of gate-source voltage of driving transistor

### 6. Conclusions

We devised a novel pixel circuit for compensating threshold variation in a driver transistor using a back-gate. We demonstrated that threshold variation was suppressed within approximately 10%, and succeeded in fabricating a 5.29-in Quad-VGA OLED display.

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